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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

Hiroyuki YANO, et al. : EXAMINER: D. DEO

SERIAL NO: 09/531,163 :

FILED: MARCH 17, 2000 : GROUP ART UNIT: 1765



FOR: AQUEOUS DISPERSION, AQUEOUS  
DISPERSION FOR CHEMICAL  
MECHANICAL POLISHING USED  
FOR MANUFACTURE OF  
SEMICONDUCTOR DEVICES,  
METHOD FOR MANUFACTURE OF  
SEMICONDUCTOR DEVICES, AND  
METHOD FOR FORMATION OF  
EMBEDDED WIRING

**RECEIVED**

MAR 04 2002

**TC 1700**

AMENDMENT AND REQUEST FOR RECONSIDERATION

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

Responsive to the Office Action of December 4, 2001, Applicants respectfully request  
reconsideration in view of the following remarks.

IN THE CLAIMS

Please cancel claims 61-75.

REMARKS

Applicants thank Examiner Deo for the helpful and courteous interview of December  
20, 2001 with Applicants' U.S. representative. During the interview the unobviousness of the  
presently claimed invention was discussed. It was noted that the molecular weight of the